

ABSTRACT

An assembly is disclosed that includes an etched hole-fill standoff; a tooling plate contacting the etched hole-fill stand-off, the stand-off and tooling plate being aligned to each other; a device having holes to be filled removably contacting the stand-off, the stand-off and device being aligned to each other; the device and the stand-off each having at least one hole, the hole of the device being aligned with the hole of the stand-off. An assembly is also disclosed comprising an etched hole-fill standoff, the stand-off comprising an etched layer bonded to a non-etched layer. A method of filling holes in a substrate having a plurality of holes to be filled includes the steps of providing an etched hole-fill stand-off, aligning the stand-off to a tooling plate, aligning the substrate to the stand off and placing the substrate in contact with the stand-off, and filling the plurality of holes of the substrate.

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